

FEATURE

- ✧ Plastic package.
- ✧ Glass passivated chip junction in SMA Package
- ✧ Excellent clamping capability.
- ✧ Low zener impedance.
- ✧ 400W peak pulse power capability on 10/1000 μ s waveform.
- ✧ Typical IR less than 1 μ A above 13V.
- ✧ Fast response time: typically less than 1.0ps from 0 Volts to BV min.
- ✧ High temperature soldering guaranteed: 265 $^{\circ}$ C/10 seconds

MECHANICAL DATE

- ✧ Case: JEDEC SMA Molded Plastic.
- ✧ Terminals: Axial leads, solderable per MIL-STD-750, Method 2026.
- ✧ Polarity: Color band denoted cathode except bidirectional.
- ✧ Mounting Position: Any.

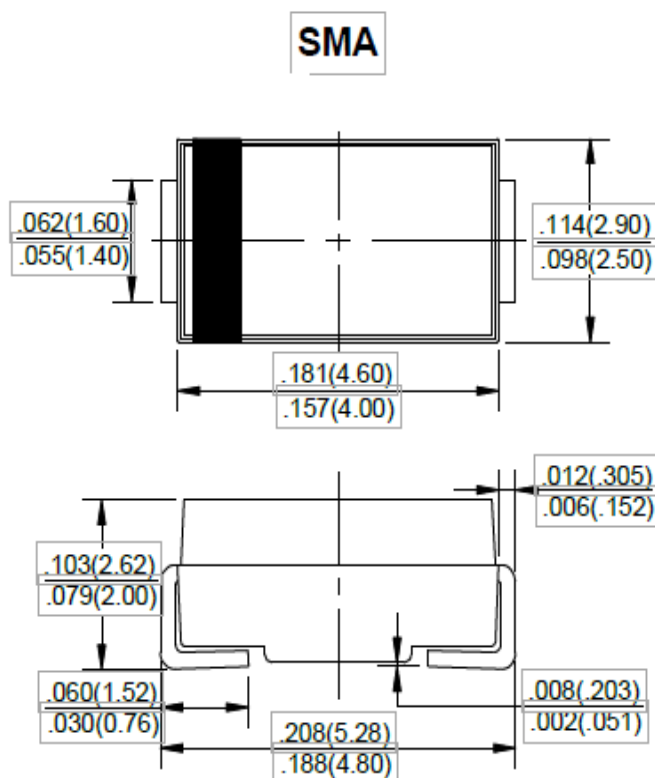
MAXIMUM RATINGS AND CHRACTERISTICS

Ratings at 25 $^{\circ}$ C ambient temperature unless otherwise specified.

RATING	SYMBOL	VALUE	UNITS
Peak Pulse Power Dissipation on 10/1000us waveform (Notel, Fig.1).	P _{PPM}	Minimum 400	Watts
Peak Pulse Current of on 10/1000us waveform. (Notel, Fig.3)	I _{PPM}	See Table	Amps
Steady State Power Dissipation at TL =75 $^{\circ}$ C, Lead lengths. 375", (9.5mm) (Fig. 5).	P _{M(AV)}	3.3	Watts
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load, (JEDEC Method) (Note 2, Fig. 6).	I _{FSM}	40	Amps
Operating junction and Storage Temperature Range.	T _J , T _{STG}	-55 to +150	$^{\circ}$ C

Notes:

1. Non-repetitive current pulse, per Fig. 3 and derated above TA = 25 $^{\circ}$ C per Fig. 2.
2. 8.3ms single half sine-wave, or equivalent square wave, Duty cycle = 4 pulses per minutes maximum.



Dimensions in inches and (millimeters)

ELECTRICAL CHARACTERISTICS

Part Number	Marking	Reverse Stand-Off Voltage	Breakdown Voltage NIN.@IT	Breakdown Voltage MAX.@IT	Reverse Leakage @VRWM	Test Current	Peak Pulse Current	Maximum Clamping Voltage @IPP
BI	BI	VR(V)	VBL(V)	VBH(V)	IR(uA)	IT(mA)	IPP(A)	VCH(V)
SMAJ6.8CA	WK	6.5	7.22	7.98	500	10	35.7	11.2

RATINGS AND CHARACTERISTIC CURVES ($T_A=25^\circ\text{C}$ unless otherwise noted)

